Product Change Notification - GBNG-27AMWI895

Date:	31 Mar 2017
Product Category:	Linear Op Amps
Notification subject:	CCB 2889 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 120K wafer technology available in 8L TDFN package at NSEB assembly site.

Notification text:

PCN Status:
Initial notification.

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K wafer technology available in 8L TDFN package at NSEB assembly site.

Pre Change:

Assembled using gold (Au) bond wire.

Post Change:

Assembled using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB	NSEB
Wire material	Au	CuPdAu
Die attach material	8200T	8600
Molding compound material	G770HCD	G700LTD
Lead frame material	C194	C194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at NSEB assembly site.

Change Implementation Status:
In Progress

Estimated Qualification Completion Date:
August 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	March 2017					-->	August 2017				
Workweek	09	10	11	12	13		31	32	33	34	35
Initial PCN Issue Date					X						
Qual Report Availability										X	
Final PCN Issue Date										X	

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:
March 31, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_GBNG-27AMWI895_ Affected CPN.pdf
PCN_GBNG-27AMWI895_Qual Plan.pdf
PCN_GBNG-27AMWI895_Affected CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

GBNG-27AMWI895 - CCB 2889 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 120K wafer technology available in 8L TDFN package at NSEB assembly site.

Affected Catalog Part Numbers (CPN)

PCN_GBNG-27AMWI895
Catalog Part Numbers
MCP6051T-E/MNY
MCP6052T-E/MNY
MCP6061T-E/MNY
MCP6062T-E/MNY
MCP6071T-E/MNY
MCP6072T-E/MNY
MCP6232T-E/MNY
MCP6402T-E/MNY
MCP6442T-E/MNY